



ON Semiconductor®

FQP13N50C / FQPF13N50C

N-Channel QFET® MOSFET

500 V, 13 A, 480 mΩ

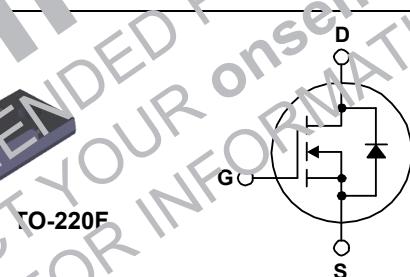
FQP13N50C / FQPF13N50C — N-Channel QFET® MOSFET

Description

These N-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.

Features

- 13 A, 500 V, $R_{DS(on)} = 48 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10 \text{ V}$, $I_D = 6.5 \text{ A}$
- Low Gate Charge (Typ. 40 pF)
- Low Crss (Typ. 1 pF)
- 100% Avalanche Tested



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQP13N50C	FQPF13N50C	Units
V_{DSS}	Drain-Source Voltage	500		V
I_D	- Continuous ($T_C = 25^\circ\text{C}$)	13	13 *	A
	- Continuous ($T_C = 100^\circ\text{C}$)	8	8 *	A
I_{DM}	Drain Current ^a	52	52 *	A
V_{GSS}	Gate-Source Voltage	± 30		V
E_{AS}	Single Pulsed Avalanche Energy	860		mJ
I_{AR}	Avalanche Current	13		A
E_{AR}	Repetitive Avalanche Energy	19.5		mJ
dv/dt	Peak Diode Recovery dv/dt	4.5		V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	195	48	W
	- Derate above 25°C	1.56	0.39	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		$^\circ\text{C}$

^a Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FQP13N50C	FQPF13N50C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.64	2.58	$^\circ\text{C}/\text{W}$
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	$^\circ\text{C}/\text{W}$

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP13N50C-F105	FQP13N50C	TO-220	Tube	N/A	N/A	50 units
FQPF13N50C-F105	FQPF13N50C	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics $T_c = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	500	--	--	V
$\Delta V_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.5	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 500 \text{ V}$, $V_{GS} = 0 \text{ V}$	--	--	--	μA
		$V_{DS} = 400 \text{ V}$, $T_c = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	100	nA

On Characteristics

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	0	--	4.0	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$, $I_D = 13 \text{ A}$	--	0.39	0.48	Ω
g_{FS}	Forward Transconductance	$V_{DS} = +0 \text{ V}$, $V_{GS} = 6.0 \text{ V}$	--	15	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$f = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 0 \text{ MHz}$	--	1500	2055	pF
C_{oss}	Output Capacitance	$f = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 0 \text{ MHz}$	--	160	235	pF
C_{rss}	Reverse Transfer Capacitance	$f = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 0 \text{ MHz}$	--	20	25	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 250 \text{ V}$, $I_D = 13 \text{ A}$, $R_G = 25 \Omega$	--	25	60	ns
t_r	Turn-On Rise Time		--	100	210	ns
$t_{d(off)}$	Turn-Off Delay Time		--	130	270	ns
t_f	Turn-Off Fall Time		--	100	210	ns
Q_g	Total Gate Charge	$V_{DS} = 400 \text{ V}$, $I_D = 13 \text{ A}$, $V_{GS} = 10 \text{ V}$	--	43	56	nC
Q_{gs}	Gate-Source Charge		--	7.5	--	nC
Q_{gd}	Gate-Drain Charge		(Note 4)	18.5	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	13	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	52	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}$, $I_S = 13 \text{ A}$	--	--	1.4	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}$, $I_S = 13 \text{ A}$, $dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	410	--	ns
Q_{rr}	Reverse Recovery Charge		--	4.5	--	μC

Notes:

1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. $L = 6 \text{ mH}$, $I_{AS} = 13 \text{ A}$, $V_{DD} = 50 \text{ V}$, $R_G = 25 \Omega$, starting $T_J = 25^\circ\text{C}$.
3. $I_{SD} \leq 13 \text{ A}$, $di/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, starting $T_J = 25^\circ\text{C}$.
4. Essentially independent of operating temperature.

Typical Characteristics

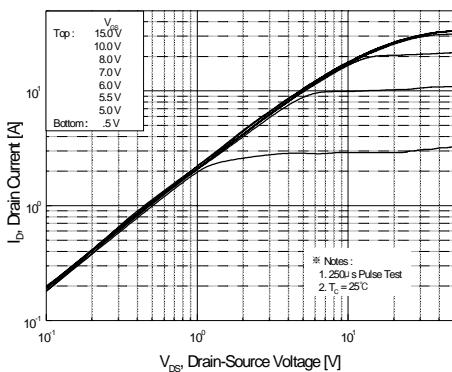


Figure 1. On-Region Characteristics

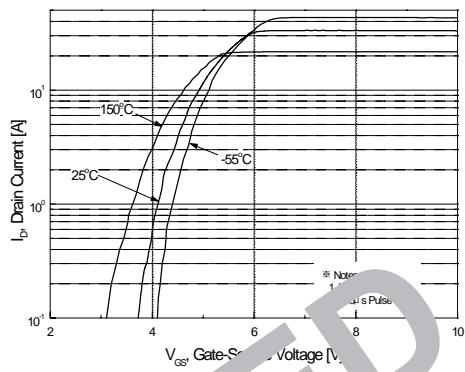


Figure 2. Transfer Characteristics

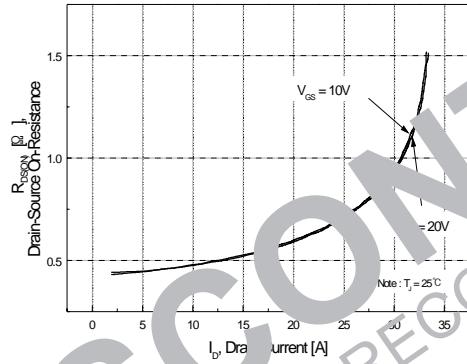


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

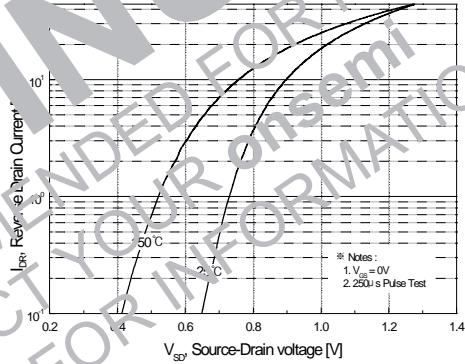


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

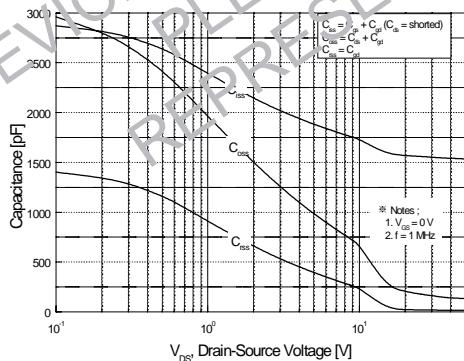


Figure 5. Capacitance Characteristics

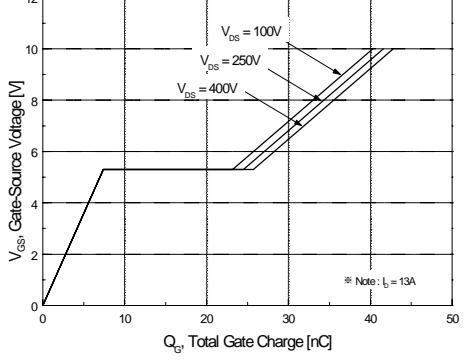


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)

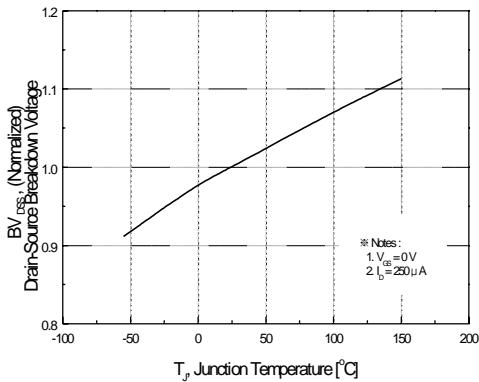


Figure 7. Breakdown Voltage Variation
vs Temperature

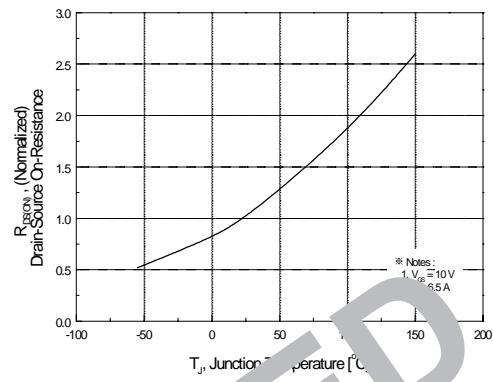


Figure 8. On-Resistance Variation
vs Temperature

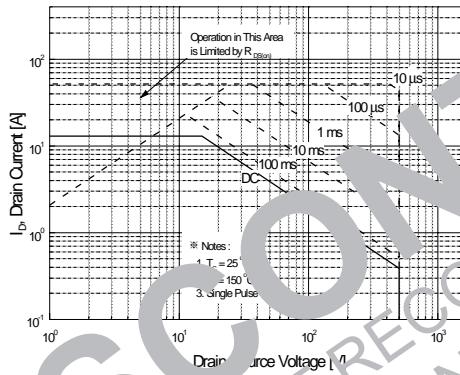


Figure 9-1. Maximum Safe Operating Area
for FQP13N50C

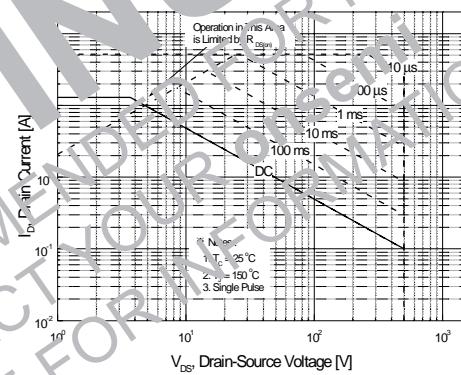


Figure 9-2. Maximum Safe Operating Area
for FQPF13N50C

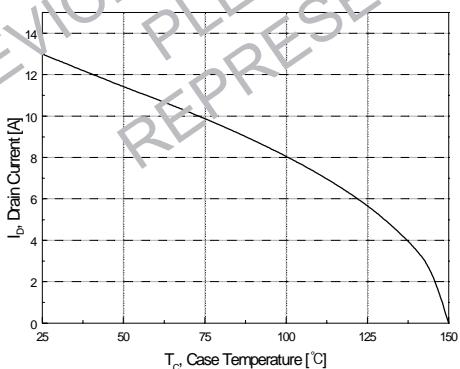


Figure 10. Maximum Drain Current
vs Case Temperature

Typical Characteristics (continued)

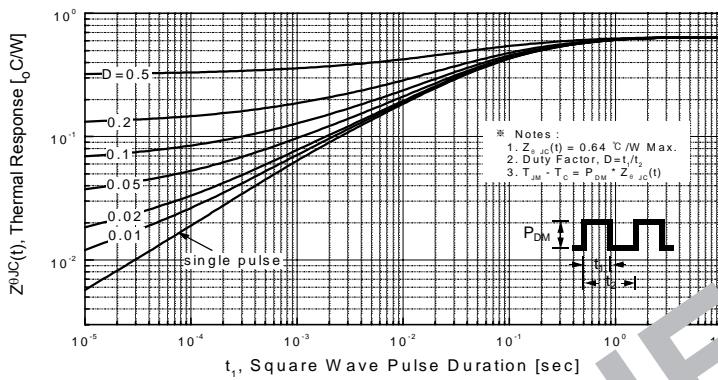


Figure 11-1. Transient Thermal Response Curve for FQP13N50C

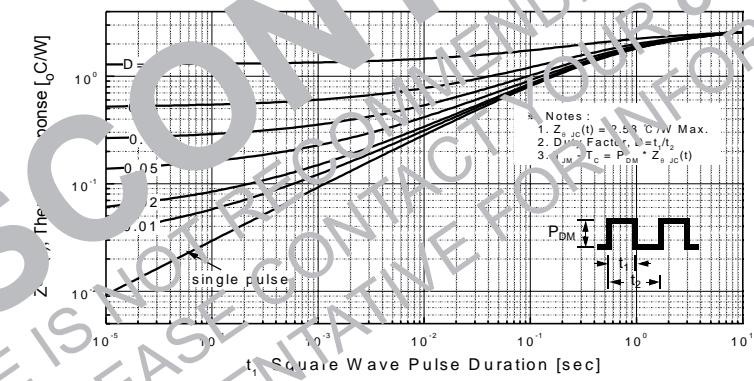


Figure 11-2. Transient Thermal Response Curve for FQPF13N50C

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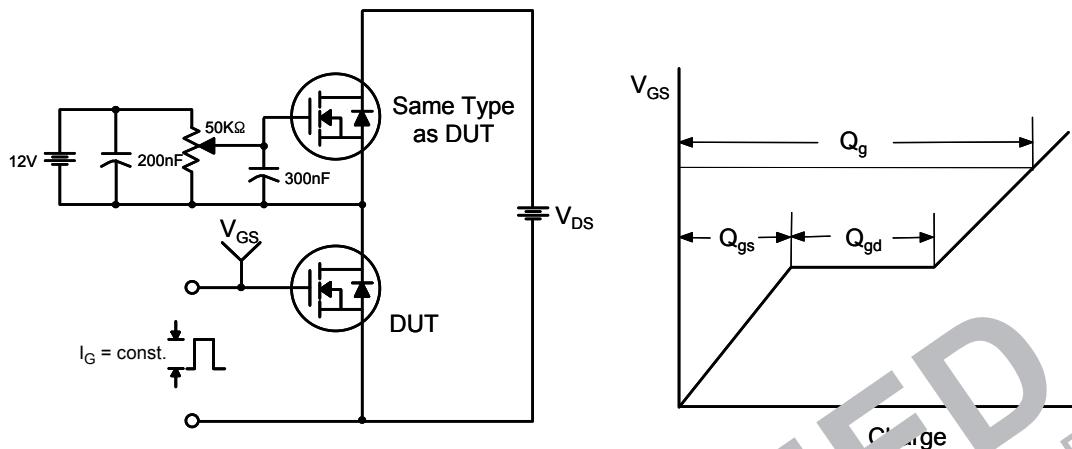


Figure 12. Gate Charge Test Circuit & Waveform

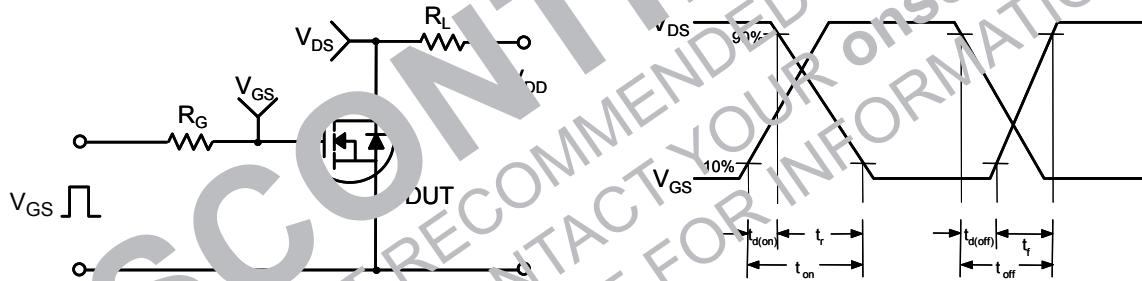


Figure 13. Resistive Switching Test Circuit & Waveforms

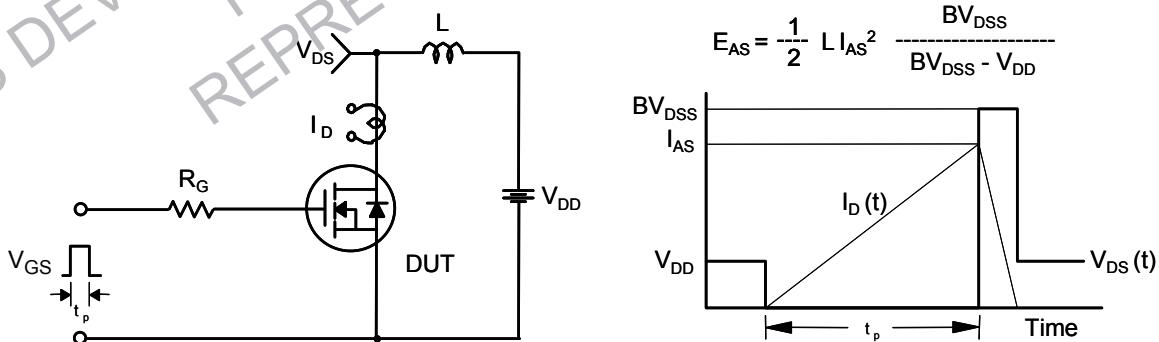


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

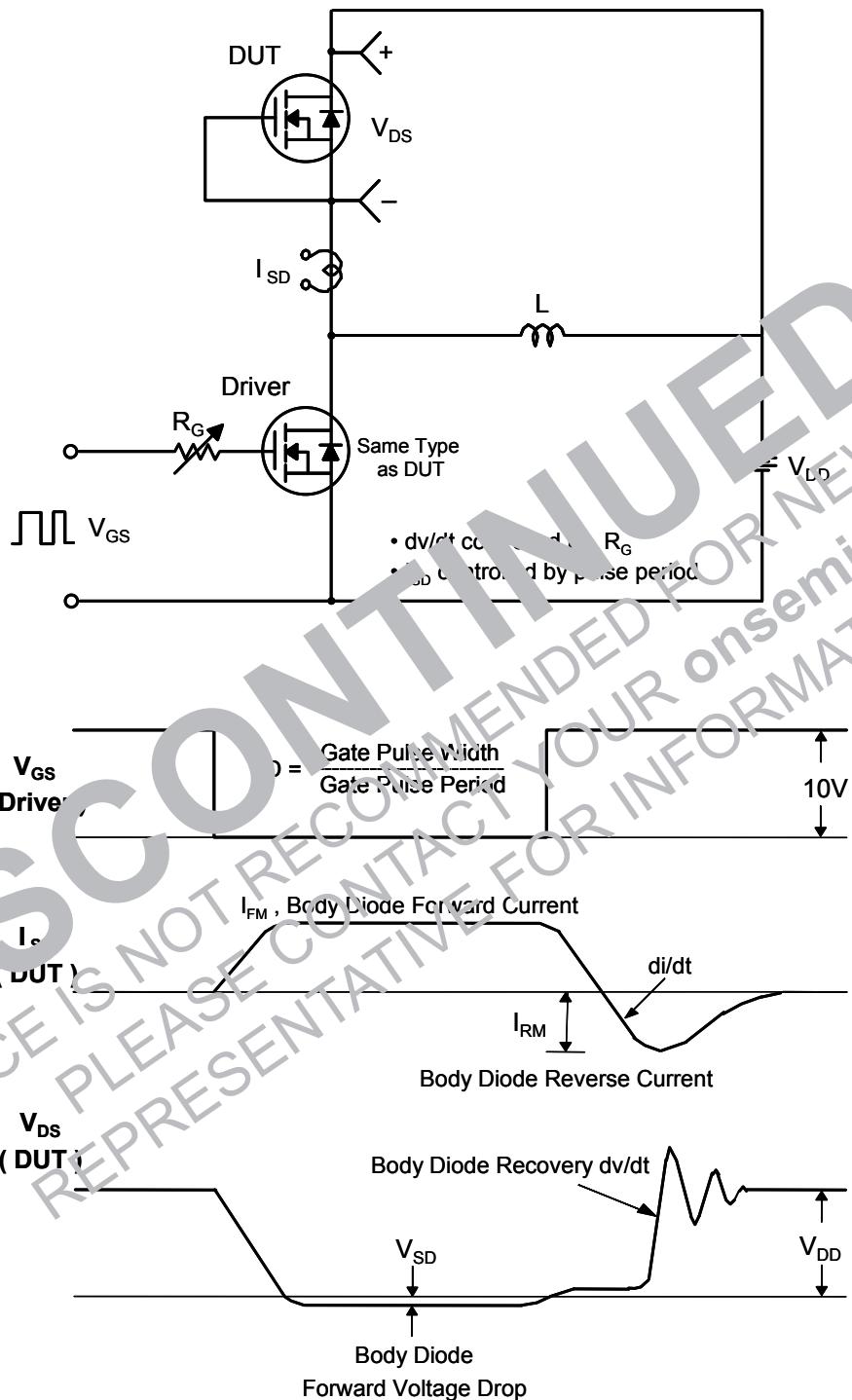


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions

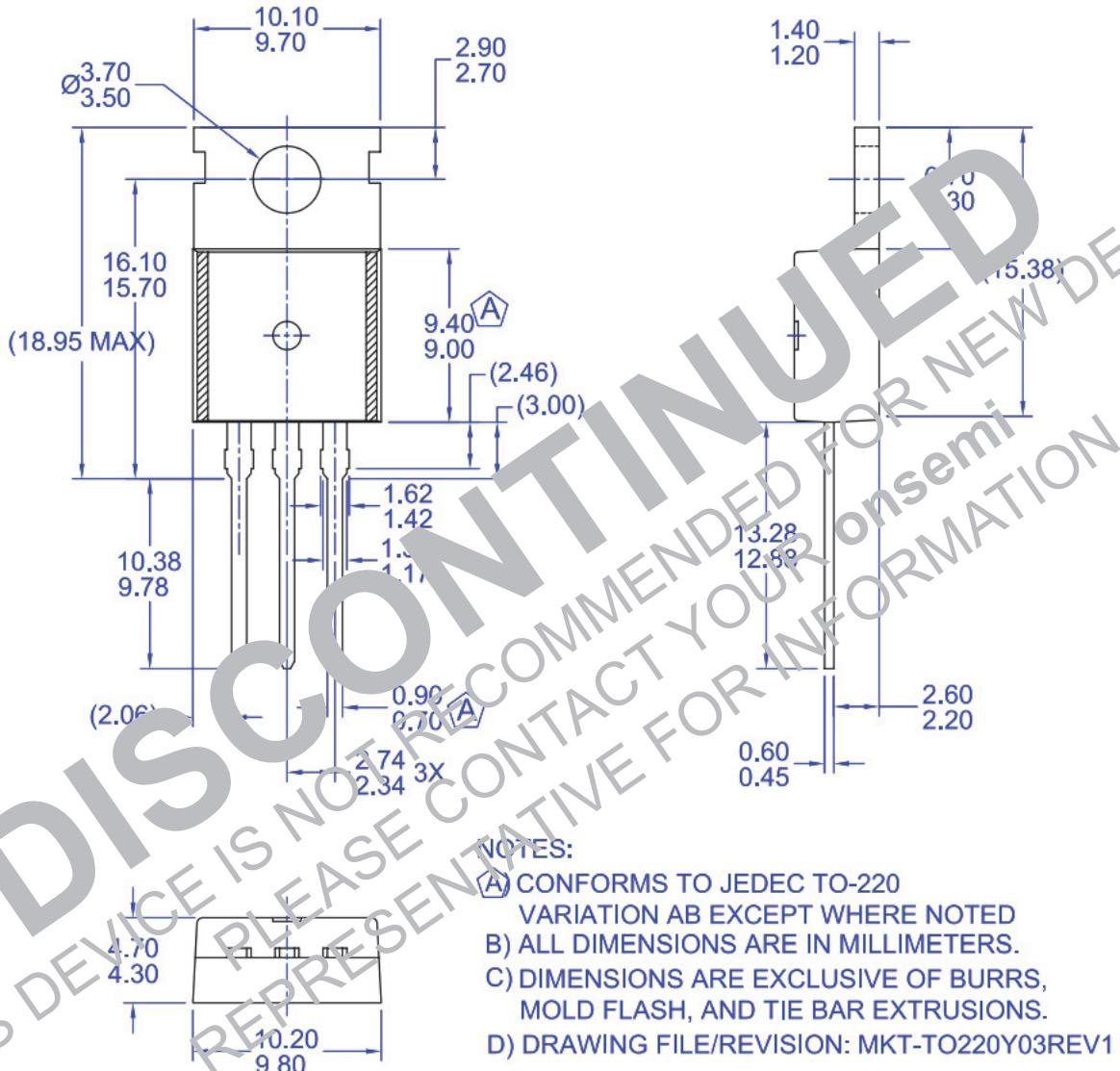


Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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Mechanical Dimensions

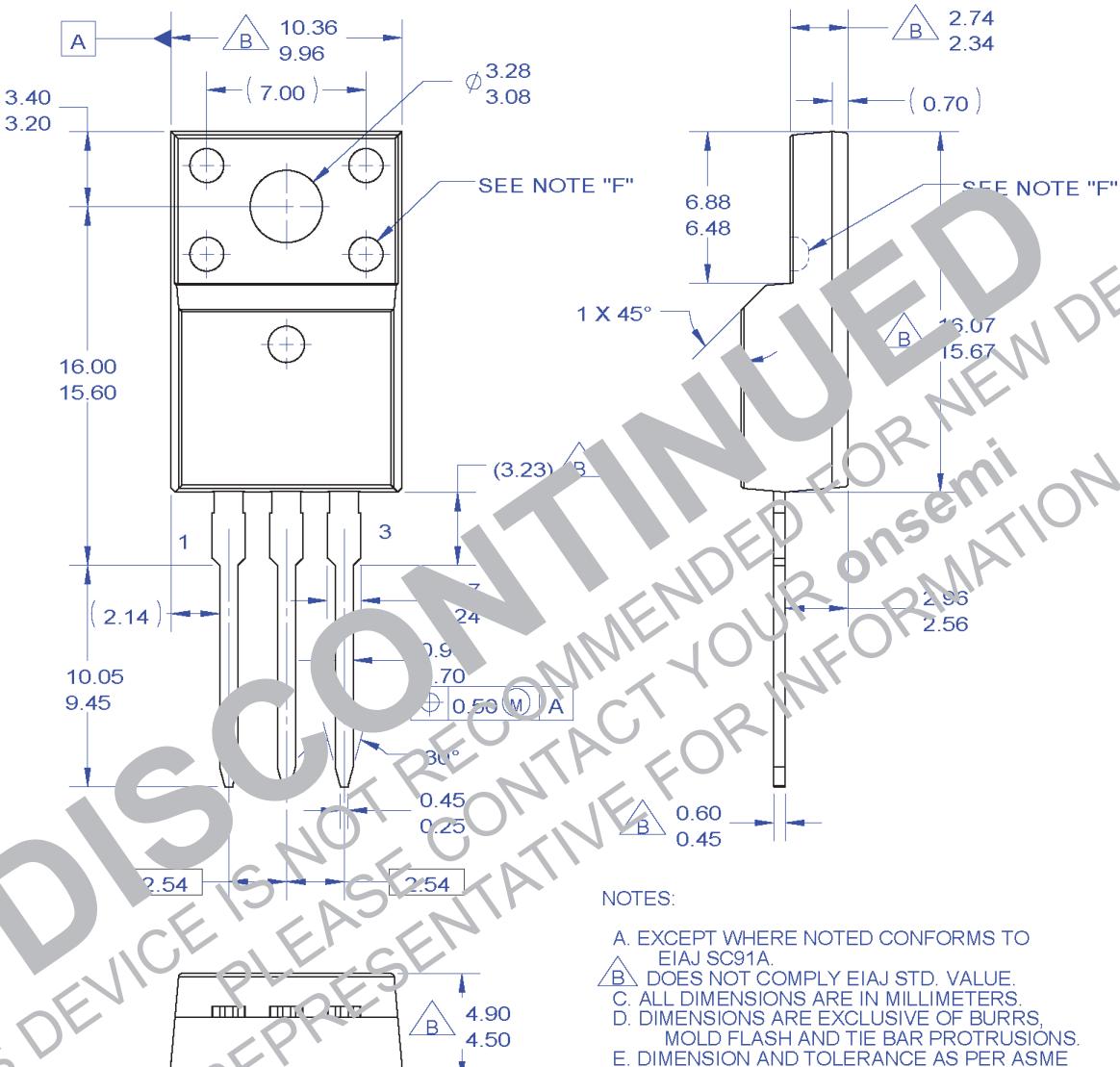


Figure 17. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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